

SPECIFICATIONS FOR REFOND SURFACE MOUNT LED

Model: **RF-P1B175TS-B29**

Company Name:	
Confirmed By Customer:	
DATE:	

深圳市瑞豐光電子有限公司

SHENZHEN REFOND OPTOELECTRONICS CO.,LTD.

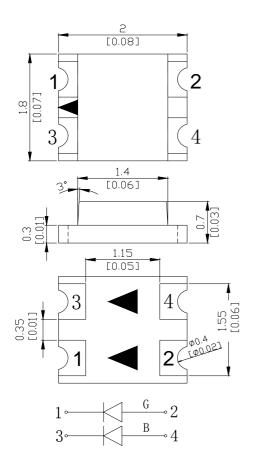
深圳市龍華和平西路特發高新科技園B2棟 B2 wing, Tefa Tech. Industry, West Heping Road, Longhua Town, Shenzhen, China P.C:518109 TEL:0755-29675000 FAX:0755-29675111 http://www.refond-led.com

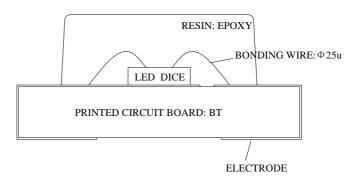


Feature

- ◆ Viewing angle:140 deg
- ◆ The materials of the LED dice is InGaN
- ◆ 2.00mm×1.80mm×0.70mm SMT-LED
- ◆ RoHS compliant lead-free soldering compatible

Package Outline







NOTES:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are ± 0.1 mm (0.004inch) unless otherwise noted.

PREPARED BY:	CHECKED BY:	APPROVED BY:
DATE:	DATE:	DATE:

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Absolute maximum ratings at Ta=25 $^{\circ}$ C

Parameter	Symbol	Va	Unit	
r ai ailletei		В	G	Ullit
Power dissipation (two circuit)	Pd	87.5	87.5	mW
Forward current	lf	25		mA
Reverse voltage	Vr	5		V
Operating temperature range	Тор	-30 ~+80		${\mathbb C}$
Storage temperature range	Tstg	-40~+100		$^{\circ}$
Pulse Forward Current	lfp	100		mA
Electrostatic Discharge	ESD	1000(HBM)		V

Electro-optical characteristics at Ta=25 $^{\mbox{\scriptsize \mathbb{C}}}$

Parameter	Toot Condition	Symbol		Value			Unit
Parameter	Parameter Test Condition Symbol		IDOI	Min.	Тур.	Max.	Offic
Wayalangth at pack amission	If 00 A	λpeak	В				nm
Wavelength at peak emission	lf=20mA		G	<u></u>			
Spectral Half bandwidth	If-20m A	Δλ	В		30		- nm
Spectral Half bandwidth	If=20mA		G		35		
Forward voltage	If=20mA	A Vf	В	2.9		3.5	- V
			G	3.0		3.5	
Dominant wayalanath	If=20mA	λd	В	465		475	nm
Dominant wavelength	II-ZUIIIA	Λ	G	520		530	nm
Luminous intensity	If=20mA	l	В		60	90	mcd
		If=20mA Iv	G		220	260	mcd
Viewing angle at 50% lv	If=10mA	2 01/2			140		Deg
Reverse current	Vr=5V	l	r			10	μΑ

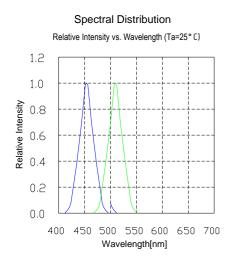
NOTE: (Tolerance: Iv $\pm 10\%$, λ_d $\pm 2nm$, Vf $\pm 0.05V$)

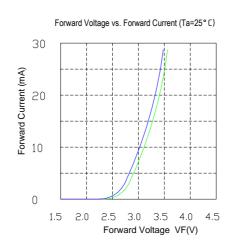
IFP Conditions : Pulse Width \leq 10msec. and Duty \leq 1/10.

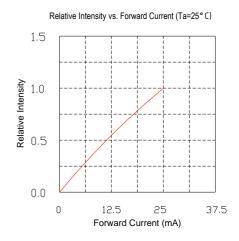
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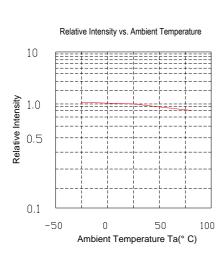


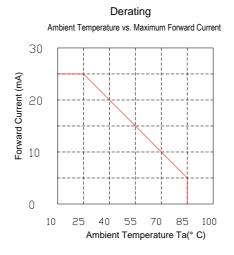
Typical optical characteristics curves











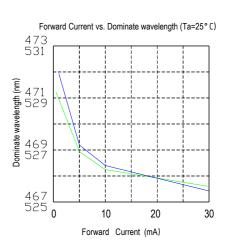
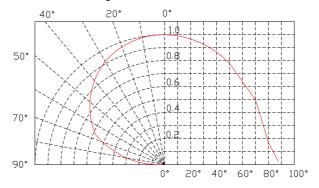


Diagram characteristics of radiation



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Reflow profile

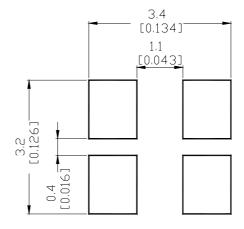
- Soldering condition
 - · Recommended soldering conditions

Reflow Soldering		Hand Soldering		
Pre-heat	160∼180℃	Temperature	300°C Max.	
Pre-heat time	120 seconds Max.			
Peak temperature	260°C Max.	Soldering time	3 second Max.	
Soldering time	10 seconds Max.		(one time only)	
Condition	Refer to Temperature-profile			

- After reflow soldering rapid cooling should be avoided
- Temperature-profile (Surface of circuit board)
 Use the following conditions shown in the figure.

REFLOW PROFILE 10 SEC. MAX. MAX 260 FEMPERATURE C° 230 above 220°C 200 120 SEC. MAX 80sec max 170 140 110 80 50 20 0 90 180 240 TIME (SECONDS)

RECOMMEND PAD DESIGN (Units: mm)



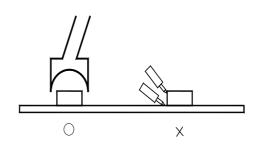
- 1. Reflow soldering should not be done more than two times
- 2. When soldering ,do not put stress on the LEDs during heating

Soldering iron

- 1. When hand soldering, keep the temperature of the iron under 300 ℃, and at that temperature keep the time under 3 sec.
- 2. The hand soldering should be done only a time
- 3. The basic spec is ≤5 sec. when the temperature of 260 °C, do not contact the resin when hand soldering

■ Rework

- 1. Customer must finish rework within 5 sec under 260 °C
- 2. The head of iron can not touch the resin
- 3. Twin-head type is preferred.



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Reliability

(1)TEST ITEMS AND RESULTS

Туре	Test Item	Test Conditions	Note	Number of Damaged
	Resistance to Soldering Heat(Reflow Soldering)	Tsld=260°C,10sec	2 times	0/22
	Temperature Cycle	-20°C 30min ↑↓5min 80°C 30min	100 cycle	0/100
Environmental Sequence	Thermal Shock	-20℃ 15min ↑↓ 80℃ 15min	100 cycle	0/100
nviror Sequ	High Temperature Storage	T _a =80°C	1000 hrs	0/100
ji Li	Temperature Humidity Storage	T _a =60°C RH=90%	1000 hrs	0/100
	Low Temperature Storage	T _a =-30°C	1000 hrs	0/100
	Power On/off Cycle Test IF=20mA	On 2 hours ↑↓ Off 10min	100 cycle	0/100
Operation Sequence	Life Test	fe Test $ \begin{array}{c c} & T_a = 25^{\circ}\!$		0/100
	High Humidity Heat Life Test	60℃ RH=90% I _F =20mA	500 hrs	0/100
	Low Temperature Life Test	T _a =-20℃ I _F =20mA	1000 hrs	0/100
	Drop	75cm	3 times	0/10

(2)CRITERIA FOR JUDGING THE DAMAGE

ltem	Symbol	Test Conditions	Criteria for Judgement		
item	Зушьы	rest conditions	Min.	Max.	
Forward Voltage	VF	IF=10mA	_	U.S.L*)×1.1	
Reverse Current	IR	VR=5V	_	U.S.L*)×2.0	
Luminous Intensity	IV	IF=10mA	L.S.L**)×0.7	_	

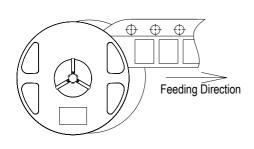
U.S.L.: Upper Standard Level L.S.L.: Lower Standard Level

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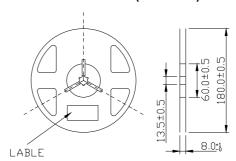


Packaging Specifications

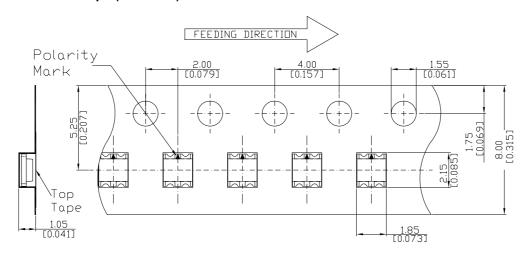
Feeding Direction



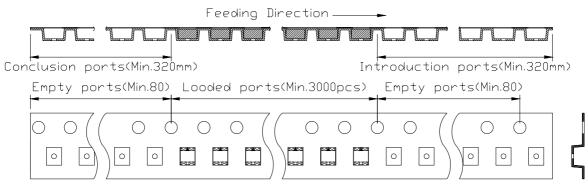
• Dimensions of Reel (Unit: mm)



• Dimensions of Tape (Unit: mm)



Arrangement of Tape



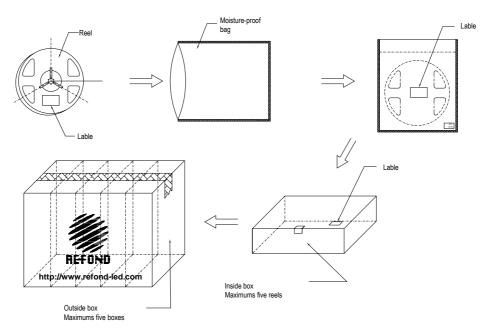
NOTES

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. 3,000 pcs/ Reel.

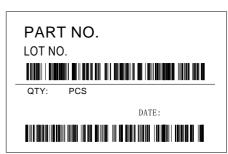
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Packaging specifications



■ Lable



CAUTIONS

Package specifications

Reeled products (numbers of products are 3,000pcs) packed in a seal off moisture-proof bag along with a desiccant one by one, Five moisture-proof bag of maximums (total maximum number of products are 15,000pcs) packed in an inside box (size: about 250mm x about 250 x about 68mm) and Five inside boxes of maximums are put the outside box (size: about 360mm x about 265mm x about 255mm) Together with buffer material, and it is packed. (Pare No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. And quantity should appear on the label on the cardboard box.) The number of the loading steps of outside box (cardboard box) has three steps.

Storage conditions

Before opening the package:

The LEDs should be kept at 30° C or less and 90%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material (silica gel) is recommended.

After opening the package:

The LEDs should be kept at 30°C or less and 70%RH or less. The LEDs should be soldered within 168 hours (7days) after opening the package. If unused LEDs remain, they should be stored in moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.

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